



<b>Title of Change:</b>	Revision of Case Outline 506AX.
<b>Effective date:</b>	25 Aug 2020
<b>Contact information:</b>	Contact your local ON Semiconductor Sales Office or <a href="mailto:IgnatiusPillay.FelixAmbrose@onsemi.com">IgnatiusPillay.FelixAmbrose@onsemi.com</a>
<b>Type of notification:</b>	This Product Bulletin is for notification purposes only. ON Semiconductor will proceed with implementation of this change upon publication of this Product Bulletin.
<b>Change Category:</b>	New revision of Case Outline 506AX
<b>Change Sub-Category(s):</b>	Datasheet/Product Doc change

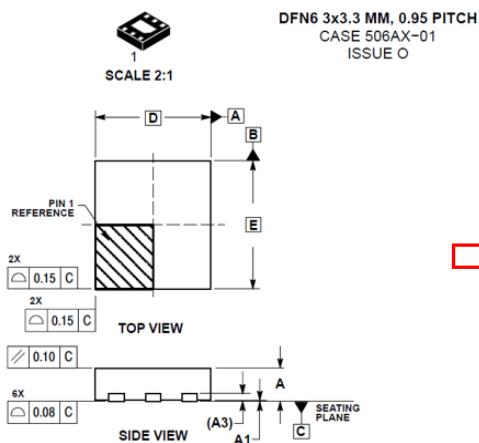
**Sites Affected:**

<b>ON Semiconductor Sites</b>	<b>External Foundry/Subcon Sites</b>
None	None

**Description and Purpose:**

To change the A dimension, package thickness from 0.80mm to 0.90mm to 0.80mm to 1.00mm for case 506AX.  
 No change to solder footprint is required. There is no material or manufacturing change; this is a document update only to align to standards and manufacturing capability

**MECHANICAL CASE OUTLINE**  
 PACKAGE DIMENSIONS



**List of Affected Standard Parts:**

**Note:** Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the [PCN Customized Portal](#).

NCV8605MN28T2G	NCV8605MN50T2G	NCV8606MN30T2G
NCV8606MN28T2G	NCV8605MN33T2G	NCV8605MN30T2G
NCV8606MN15T2G	NCV8605MN15T2G	NCV8605MN18T2G
NCV8605MN25T2G	NCV8606MN25T2G	NCV8606MN33T2G
NCV8606MN18T2G	NCV8606MN50T2G	NCV8606MNADJT2G
NCV8605MNADJT2G	NCV5661MN30T2G	NCV5661MN12T2G
NCV5661MN18T2G	NCV5661MN28T2G	NCV5661MN25T2G
NCV5661MNADJT2G	NCV5661MN15T2G	NCV5661MN33T2G



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## Appendix A: Changed Products

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Product	Customer Part Number	Qualification Vehicle	New Part Number	Replacement Supplier
NCV8605MN33T2G		NA		
NCV8605MNADJT2G		NA		
NCV5661MNADJT2G		NA		
NCV5661MN33T2G		NA		
NCV8606MN33T2G		NA		
NCV8606MNADJT2G		NA		